

The invention is intended for providing a semiconductor package structure which prevents degradation in characteristics of a semiconductor device and breakage of the interconnections when the semiconductor device is packaged on a circuit substrate. In the package structure having the semiconductor device mounted on the circuit substrate, bump electrodes of the semiconductor device are placed on input/output terminal electrodes of the circuit substrate and are electrically and mechanically connected thereto by bonding with conductive adhesive, and the semiconductor device is bonded and fixed to the circuit substrate by a resin film formed previously on a surface of the substrate. The structure does no damage to a semiconductor functional part and to interconnections, and allows mounting with a lower load in comparison with structures using conventional anisotropic conductive films and the like, so that heat-press bonding mounting with a high productivity and a low cost can be applied.